

### 40V COMPLEMENTARY MEDIUM POWER TRANSISTOR IN SOT26

#### **Features**

- NPN + PNP Combination
- BV<sub>CEO</sub> > 40 (-40)V
- BV<sub>ECO</sub> > 6 (-3)V
- I<sub>CM</sub> = 9 (-9)A Peak Pulse Current
- V<sub>CE(sat)</sub> < 60 (-90)mV @ 1A</li>
- $R_{CE(sat)} = 38 (58) m\Omega$
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

#### **Description**

Advanced process capability is used to achieve this high performance device. Combining NPN and PNP transistors in the SOT26 package provides a compact solution for the intended applications.

#### **Mechanical Data**

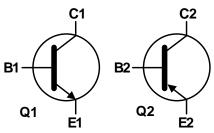
- Case: SOT26
- Case Material: Molded Plastic, "Green" Molding Compound
- UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208<sup>®</sup>
- Weight: 0.015 grams (Approximate)

#### **Applications**

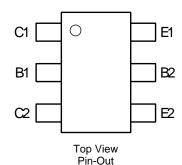
- MOSFET and IGBT Gate Driving
- Motor Drive



Top View



Device Symbol



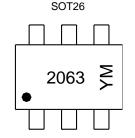
### **Ordering Information** (Note 4)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXTC2063E6TA	2063	7	8	3,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/ for more information about Diodes Incorporated's definitions of Halogen and Antimony free, "Green" and Lead-Free.
- 3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com.

### **Marking Information**



2063 = Product Type Marking Code YM = Date Code Marking Y or  $\overline{Y}$  = Year (ex: C = 2015) M or  $\overline{M}$  = Month (ex: 9 = September)

#### Date Code Key

Year	201	5	2016	2017	2018	2019	2020	202	1 20	022	2023	2024	2025
Code	С		D	E	F	G	Н	I		J	K	L	М
Mont	h	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	)	1	2	3	4	5	6	7	8	9	0	N	D





May 2015

# Absolute Maximum Ratings – Q1 (NPN Transistor) (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	130	V
Collector-Emitter Voltage	V <sub>CEO</sub>	40	V
Emitter-Collector Voltage (Reverse blocking)	V <sub>ECO</sub>	6	V
Emitter-Base Voltage	V <sub>EBO</sub>	7	V
Continuous Collector Current	Ic	3.5	A
Peak Pulsed Collector Current	Ісм	9	Α
Base Current	I <sub>B</sub>	1	Α

### Absolute Maximum Ratings - Q2 (PNP Transistor) (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	-45	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-40	V
Emitter-Collector Voltage (Reverse blocking)	V <sub>ECO</sub>	-3	V
Emitter-Base Voltage	V <sub>EBO</sub>	-7	V
Continuous Collector Current	Ic	-3	A
Peak Pulsed Collector Current	I <sub>CM</sub>	-9	A
Base Current	I <sub>B</sub>	-1	Α

### Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

Characteristic		Symbol	Value	Unit	
	(Notes 5 & 9)		0.7 5.6		
	(Notes 6 & 9)		0.9 7.2		
Power Dissipation Linear Derating Factor	(Notes 6 & 10)	P <sub>D</sub>	1.1 8.8	W mW/°C	
-	(Notes 7 & 9)		1.1 8.8		
	(Notes 8 & 9)		1.7 13.6		
	(Notes 5 & 9)		179		
	(Notes 6 & 9)		139	°C/W	
Thermal Resistance, Junction to Ambient	(Notes 6 & 10)	$R_{\theta JA}$	113		
	(Notes 7 & 9)	Ų-	113		
	(Notes 8 & 9)		73		
Thermal Resistance, Junction to Lead	(Note 11)	$R_{ heta JL}$	87.58		
Operating and Storage Temperature Range	•	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C	

### ESD Ratings (Note 12)

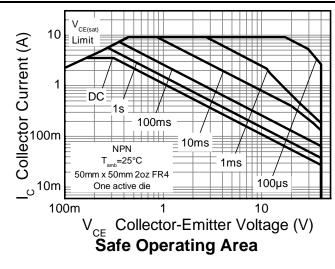
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

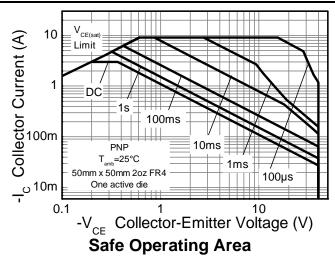
5. For a device surface mounted on 15mm x 15mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured Notes: when operating in a steady-state condition.

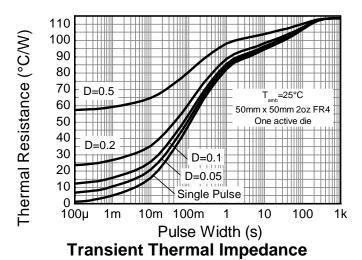
- 6. Same as Note (5), except the device is surface mounted on 25mm x 25mm 1oz copper.
- 7. Same as Note (5), except the device is surface mounted on 50mm x 50mm 2oz copper.
- 8. Same as Note (7), except the device is measured at t < 5 seconds.
- 9. For device with one active die, both collectors attached to a common heatsink.
- 10. For device with two active dice running at equal power, split heatsink 50% to each collector.
- 11. Thermal resistance from junction to solder-point (at the end of the collector lead).
- 12. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

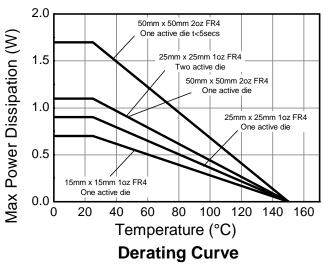


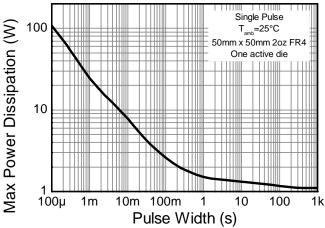
# **Thermal Characteristics and Derating Information**















# Electrical Characteristics – Q1 (NPN Transistor) (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS							
Collector-Base Breakdown Voltage	$BV_{CBO}$	130	170		V	$I_C = 100\mu A, I_E = 0$	
Collector-Emitter Breakdown Voltage (Note 13)	$BV_{CEO}$	40	63		٧	$I_C = 10 \text{mA}, I_B = 0$	
Emitter-Base Breakdown Voltage	$BV_{EBO}$	7	8.3		V	$I_E = 100 \mu A, I_C = 0$	
Emitter-Collector Breakdown Voltage (reverse blocking)	BV <sub>ECX</sub>	6	7.4		V	$I_E$ =100μA, $R_{BC}$ < 1k $\Omega$ or 0.25V > $V_{BC}$ > -0.25V	
Emitter-Collector Breakdown Voltage (base open)	BV <sub>ECO</sub>	6	7.4	_	V	$I_E = 100 \mu A$	
Collector Cutoff Current	I <sub>CBO</sub>	_	<1	50 20	nΑ μΑ	V <sub>CB</sub> = 100V V <sub>CB</sub> = 100V, T <sub>A</sub> = +100°C	
Collector Cutoff Current	I <sub>EBO</sub>	_	<1	50	nA	V <sub>EB</sub> = 5.6V	
ON CHARACTERISTICS (Note 13)							
DC Current Gain	h <sub>FE</sub>	300 280 40	450 400 60	900	_	$I_C = 10 \text{mA}, V_{CE} = 2 \text{V}$ $I_C = 1.0 \text{A}, V_{CE} = 2 \text{V}$ $I_C = 3.5 \text{A}, V_{CE} = 2 \text{V}$	
Collector-Emitter Saturation Voltage	V <sub>CE(sat)</sub>	_	50 85 150 135	60 110 220 195	mV	I <sub>C</sub> = 1.0A, I <sub>B</sub> = 100mA I <sub>C</sub> = 1.0A, I <sub>B</sub> = 20mA I <sub>C</sub> = 2.0A, I <sub>B</sub> = 40mA I <sub>C</sub> = 3.5A, I <sub>B</sub> = 350mA	
Base-Emitter Saturation Voltage	V <sub>BE(sat)</sub>	_	960	1,050	mV	$I_C = 3.5A$ , $I_B = 350mA$	
Base-Emitter Turn-On Voltage	V <sub>BE(on)</sub>	_	860	950	mV	$I_C = 3.5A, V_{CE} = 2V$	
SMALL SIGNAL CHARACTERISTICS							
Output Capacitance	$C_{obo}$		12	20	pF	$V_{CB} = 10V, f = 1.0MHz$	
Current Gain-Bandwidth Product	$f_T$		190		MHz	$V_{CE} = 10V, I_{C} = 50mA, f = 100MHz$	
Delay Time	t <sub>d</sub>		64		ns		
Rise Time	t <sub>r</sub>		108	_	ns	\/ = 10\/  - = 10  - = 10m4	
Storage Time	ts		428	_	ns	$V_{CC} = 10V, I_C = 1A, I_{B1} = I_{B2} = 10mA$	
Fall Time	t <sub>f</sub>	_	130	_	ns		

Note: 13. Measured under pulsed conditions. Pulse width  $\leq$  300 $\mu$ s. Duty cycle  $\leq$  2%.





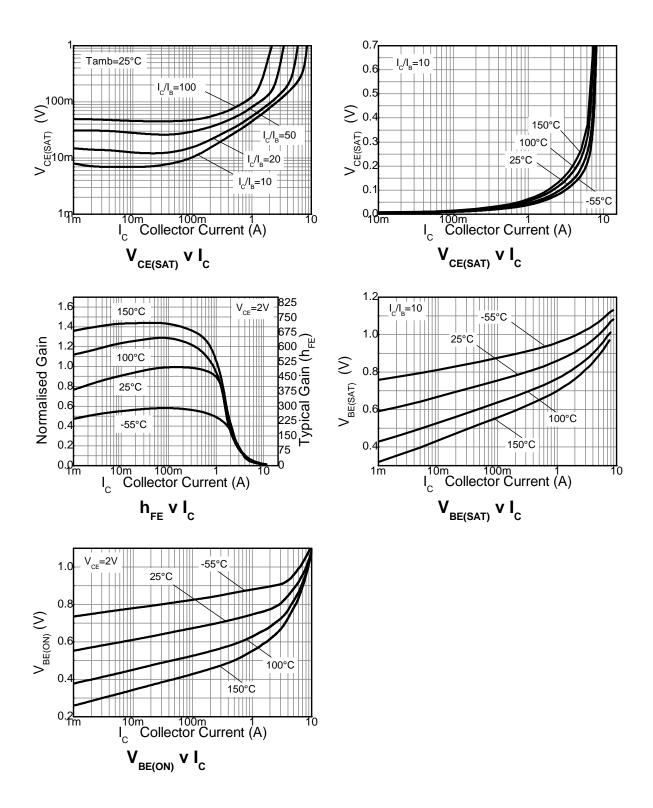
# Electrical Characteristics – Q2 (PNP Transistor) (@TA = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Collector-Base Breakdown Voltage	$BV_CBO$	-45	-80	_	V	$I_C = -100\mu A, I_E = 0$
Collector-Emitter Breakdown Voltage (Note 14)	BV <sub>CEO</sub>	-40	-65	_	V	$I_C = -10 \text{mA}, I_B = 0$
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	-7	-8.3	_	V	$I_E = -100 \mu A, I_C = 0$
Emitter-Collector Breakdown Voltage (reverse blocking)	BV <sub>ECX</sub>	-6	-7.4	_	<b>V</b>	$-I_E = 100\mu A$ , $R_{BC} < 1k\Omega$ or 0.25V < $V_{BC} < -0.25V$
Emitter-Collector Breakdown Voltage (base open)	BV <sub>ECO</sub>	-3	-8.7	_	V	$I_E = -100 \mu A$
Collector Cutoff Current	lana	_	<1	-50	nA	V <sub>CB</sub> = -36V
Collector Cutoff Current	I <sub>CBO</sub>	_		-20	μΑ	$V_{CB} = -36V, T_A = +100^{\circ}C$
Collector Cutoff Current	I <sub>EBO</sub>		<1	-50	nA	$V_{EB} = -5.6V$
ON CHARACTERISTICS (Note 14)						
		300	450	900		$I_C = -10 \text{mA}, V_{CE} = -2 \text{V}$
DC Current Gain	h <sub>FE</sub>	200	280	_	_	$I_C = -1.0A$ , $V_{CE} = -2V$
		20	50	_		$I_C = -3.0A$ , $V_{CE} = -2V$
		_	-70	-90		$I_C = -1.0A$ , $I_B = -100mA$
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	_	-195		mV	$I_C = -1.0A$ , $I_B = -20mA$
	` ,		-175			$I_C = -3.0A$ , $I_B = -300mA$
Base-Emitter Saturation Voltage	V <sub>BE(sat)</sub>		-935	-1,000	mV	$I_C = -3.0A$ , $I_B = -300mA$
Base-Emitter Turn-On Voltage	V <sub>BE(on)</sub>		-855	-950	mV	I <sub>C</sub> = -3.0A, V <sub>CE</sub> = -2V
SMALL SIGNAL CHARACTERISTICS						
Output Capacitance	$C_{obo}$		17	25	pF	$V_{CB} = -10V, f = 1.0MHz$
Current Gain-Bandwidth Product	f⊤		270	_	MHz	V <sub>CE</sub> = -10V, I <sub>C</sub> = -50mA, f = 100MHz
Delay Time	t <sub>d</sub>		57	_	ns	
Rise Time	t <sub>r</sub>	_	69	_	ns	\
Storage Time	ts		154	_	ns	$V_{CC} = -10V$ , $I_{C} = -1A$ , $I_{B1} = I_{B2} = -10mA$
Fall Time	t <sub>f</sub>	_	60	_	ns	

Note: 14. Measured under pulsed conditions. Pulse width  $\leq$  300 $\mu$ s. Duty cycle  $\leq$  2%.

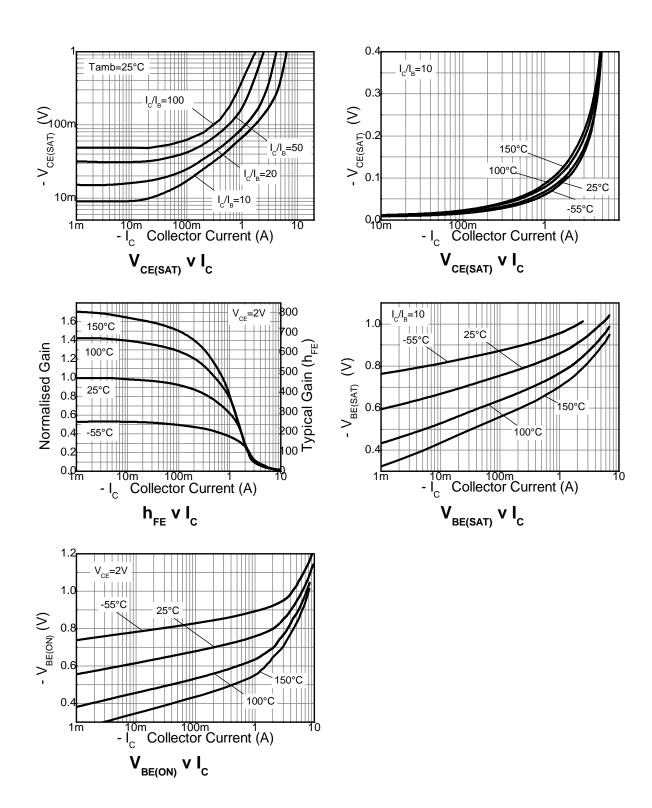


# Typical Electrical Characteristics – Q1 (NPN Transistor) (@TA = +25°C, unless otherwise specified.)





# Typical Electrical Characteristics – Q2 (PNP Transistor) (@T<sub>A</sub> = +25°C, unless otherwise specified.)

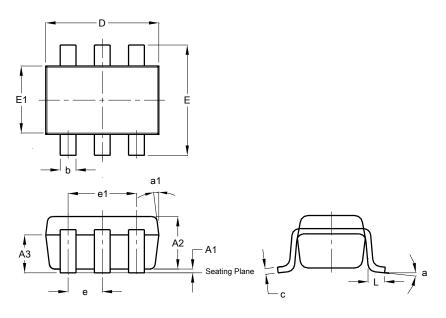




# **Package Outline Dimensions**

Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.

#### SOT26

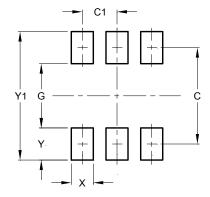


	SC	SOT26							
Dim	Min	Max	Тур						
A1	0.013	0.10	0.05						
A2	1.00	1.30	1.10						
A3	0.70	0.80	0.75						
b	0.35	0.50	0.38						
С	0.10	0.20	0.15						
D	2.90	3.10	3.00						
е	-	-	0.95						
e1	-	-	1.90						
Е	2.70	3.00	2.80						
E1	1.50	1.70	1.60						
L	0.35	0.55	0.40						
а	а -		8°						
a1		-	7°						
All	Dimen	sions	in mm						

# **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.

#### SOT26



Dimensions	Value (in mm)
С	2.40
C1	0.95
G	1.60
X	0.55
Y	0.80
Y1	3.20





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